





24th/25th March 2020 // Ingolstadt

AGENDA

Reliability Testing and Protection

Day 1 // 24th March

Dr. Helmut Schweigart 13.30 // Welcome

- Head of Reliability & Surfaces Introduction of the agenda, ZESTRON and GfKORR
 - **ZESTRON Europe** Introduction of participants

Chief Technology Officer Gen3 Systems

Emma Hudson 14.00 // Standardization and Trends/Needs concerning EIS Weak Spots of today's SIR Testing

- Current standards in use for surface ECM testing and their weaknesses
- How is EIS starting to appear in the electronics industry standards
- What should be considered when developing new EIS standards for international use

Head of Reliability & Surfaces - Introduction into method

Dr. Helmut Schweigart 14.45 // Impedance Spectroscopy

- **ZESTRON Europe** Chances in electronics
 - Cases and first experiences

15.30 // Coffee Break

Group Leader Electrochemistry - Introduction of degradation mechanism

Dr. Michael Schneider 16.00 // Risk Assessment at Mold Applications

- Fraunhofer IKTS Non-destructive test methods
 - Examples

16.45 // Final Discussion of Day 1

17.00 // End of Day 1

Sightseeing & Dinner

18.30 // City Tour

Meeting point at Taschenturmtor in Ingolstadt (duration approx. 1 hour)

19.30 // Dinner

Exchange of experiences during a joint dinner in a Bavarian Restaurant







AGENDA

Reliability Testing and **Protection**

Day 2 // 25th March

Dr. Helmut Schweigart 09.00 // Summary of the day

Head Corporate Analytics & Testing

Dr. Joerg Vogelsang 09.15 // Use of EIS in the context of heavy duty corrosion protective organic coatings

- Sika Technology AG Expectations and promises
 - Limitations and opportunities
 - Realistic target setting and the power of EIS

10.15 // Coffee Break

Mounting & Connection Technology Substrate & Control

Dr. Theresia Richter 10.40 // Impedance Spectroscopy as alternative Detection Method for Reliability and Humidity Robustness of PCBAs

Robert Bosch GmbH

- Unit Risk for electrochemical migration assessed by electrochemical impedance spectroscopy
 - Perspectives of impedance spectroscopy for testing of solder joint reliability and PCBA humidity robustness

11.40 // Lunch

Professor in Corrosion and Surface Engine Technical University of Denmark

Rajan Ambat 12.40 // Use of EIS for risk assessment of flux residues and humidity absorption risk on PCBAs

- PCBA cleanliness as a means to induce humidity robustness
- **DTU** EIS as a method for assessing flux chemistry moisture absorption
 - Residue and moisture induced risk prediction How EIS and DC methods
 - EIS for detecting humidity absorption and moisture transport

Freddy Gilbert 13.40 // Material Compatibility Check Abilities

Technology Analyst - Visual Inspection

- zestron Europe SEM-EDS and FTIR-Spectroscopy
 - Impedance Spectroscopy

14.10 // Coffee Break

Graham Naisbitt 14.30 // Outlook to new EIS based Testing Procedures

- Managing Director Considerations when developing new EIS test procedures
 - Gen3 Systems Getting the industry to adopt new test procedures
 - EIS testing for 'objective evidence'

15.00 // Final Discussion

15.15 // End of Event







Reliability Testing and Protection

24th/25th March 2020 // Ingolstadt // Germany

To register, please fill out the following form and send it to gfkorr@dechema.de

Participant:	Mrs. O	Mr. O
Surname:		
First name:		
Title, Position:		
Company:		
Phone:		
Fax:		
E-mail:		
Invoice address: Company:		
Department:		
Street:		
Postcode, City:		
Country:		
Participation fee (please Member of EFC 800 Eu		≣uro
he participation fee includes:		

Proceedings in printed form
Refreshments / Coffee breaks
Social Programme / City Tour

Dinner on the first evening

Lunch buffet on the second day (salad buffet, various starters, main course, dessert)

I have been informed about the privacy policy for the usage of this service. I have also been informed on my right to object to the use of my data at any time.

(for full details click the link: http://www.gfkorr.de/datenschutz.html)